

FDI8442

N-Channel PowerTrench® MOSFET 40V, 80A, 2.9m Ω

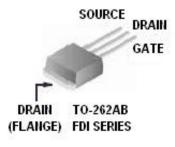
Features

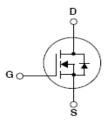
- Typ $r_{DS(on)} = 2.3m\Omega$ at $V_{GS} = 10V$, $I_D = 80A$
- Typ $Q_{g(10)} = 181nC$ at $V_{GS} = 10V$
- Low Miller Charge
- Low Q_{rr} Body Diode
- UIS Capability (Single Pulse and Repetitive Pulse)
- Qualified to AEC Q101
- RoHS Compliant

Applications

- Automotive Engine Control
- Powertrain Management
- Solenoid and Motor Drivers
- Electronic Steering
- Integrated Starter / Alternator
- Distributed Power Architectures and VRMs
- Primary Switch for 12V Systems







$\textbf{MOSFET Maximum Ratings} \ \, \textbf{T}_{C} = 25^{\circ}\text{C unless otherwise noted}$

Symbol	Parameter	Ratings	Units
V _{DSS}	Drain to Source Voltage	40	V
V _{GS}	Gate to Source Voltage	±20	V
	Drain Current Continuous (T _C <158°C, V _{GS} = 10V)	80	
I_D	Drain Current Continuous (T _{amb} = 25°C, V _{GS} = 10V, with R _{0JA} = 62°C/W) 23	Α
	Pulsed	See Figure 4	
E _{AS}	Single Pulse Avalanche Energy (Note	1) 720	mJ
В	Power Dissipation	254	W
P_D	Derate above 25°C	1.7	W/°C
T _J , T _{STG}	Operating and Storage Temperature	-55 to +175	°C

Thermal Characteristics

$R_{\theta JC}$	Thermal Resistance Junction to Case	0.59	°C/W	
$R_{\theta JA}$	Thermal Resistance Junction to Ambient	(Note 2)	62	°C/W

Package Marking and Ordering Information

Device Marking	Device	Package	Reel Size	Tape Width	Quantity
FDI8442	FDI8442	TO-262	Tube	N/A	50 units

Electrical Characteristics T_J = 25°C unless otherwise noted

Parameter

Off Ch	aracteristics						
B _{VDSS}	Drain to Source Breakdown Voltage	$I_D = 250 \mu A, V_{GS}$	3 = 0V	40	-	-	V
	Zero Gate Voltage Drain Current	V _{DS} = 32V		-	-	1	^
DSS	Zero Gate Voltage Drain Gurrent	$V_{GS} = 0V$	$T_J = 150^{\circ}C$	-	-	250	μΑ
loco	Gate to Source Leakage Current	$V_{CC} = +20V$		_	-	+100	nA

Test Conditions

Min

Тур

Max

Units

On Characteristics

Symbol

$V_{GS(th)}$	Gate to Source Threshold Voltage	$V_{DS} = V_{GS}, I_D = 250 \mu A$	2	2.9	4	V
		$I_D = 80A, V_{GS} = 10V$	-	2.3	2.9	
r _{DS(on)}	Drain to Source On Resistance	$I_D = 80A, V_{GS} = 10V,$ $T_J = 175^{\circ}C$	-	3.9	5.0	mΩ

Dynamic Characteristics

C _{iss}	Input Capacitance	V _{DS} = 25V, V _{GS} = 0V, f = 1MHz		-	12200	-	pF
C _{oss}	Output Capacitance			-	1040	-	pF
C _{rss}	Reverse Transfer Capacitance			-	640	-	pF
R_{G}	Gate Resistance	$V_{GS} = 0.5V$, $f = 1MHz$		-	1.0	-	Ω
$Q_{g(TOT)}$	Total Gate Charge at 10V	$V_{GS} = 0$ to 10V		-	181	235	nC
$Q_{g(TH)}$	Threshold Gate Charge	$V_{GS} = 0 \text{ to } 2V$	$V_{DD} = 20V$	-	23	30	nC
Q_{gs}	Gate to Source Gate Charge		I _D = 80A	•	49	-	nC
Q _{gs2}	Gate Charge Threshold to Plateau		$I_g = 1mA$	-	26	-	nC
Q_{gd}	Gate to Drain "Miller" Charge			-	41	-	nC

Electrical Characteristics $T_J = 25^{\circ}\text{C}$ unless otherwise noted

Symbo	Parameter	Test Conditions	Min	Тур	Max	Units
Switch	ing Characteristics					
t _(on)	Turn-On Time		-	-	62	ns
t _{d(on)}	Turn-On Delay Time		-	19.5	-	ns
t _r	Turn-On Rise Time	$V_{DD} = 20V, I_{D} = 80A$ $V_{GS} = 10V, R_{GS} = 2\Omega$	-	19.3	-	ns
t _{d(off)}	Turn-Off Delay Time	$V_{GS} = 10V, R_{GS} = 2\Omega$	-	57	-	ns
t _f	Turn-Off Fall Time		-	17.2	-	ns
t _{off}	Turn-Off Time		-	-	118	ns

Drain-Source Diode Characteristics

V	Source to Drain Diode Voltage	I _{SD} = 80A	-	0.9	1.25	V
V SD	V _{SD} Source to Drain Diode Voltage	I _{SD} = 40A	-	0.8	1.0	٧
t _{rr}	Reverse Recovery Time	I _F = 75A, di/dt = 100A/μs	-	49	64	ns
Q _{rr}	Reverse Recovery Charge	$I_F = 75A$, di/dt = 100A/ μ s	-	70	91	nC

1: Starting T_J = 25°C, L = 0.35mH, I_{AS} = 64A 2: Pulse width = 100s.

This product has been designed to meet the extreme test conditions and environment demanded by the automotive industry. For a copy of the requirements, see AEC Q101 at: http://www.aecouncil.com/
All Fairchild Semiconductor products are manufactured, assembled and tested under ISO9000 and QS9000 quality systems certification.

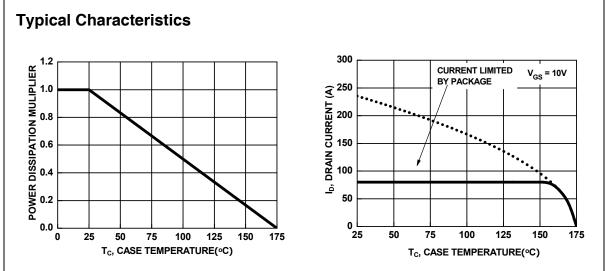


Figure 1. Normalized Power Dissipation vs Case Temperature

Figure 2. Maximum Continuous Drain Current vs Case Temperature

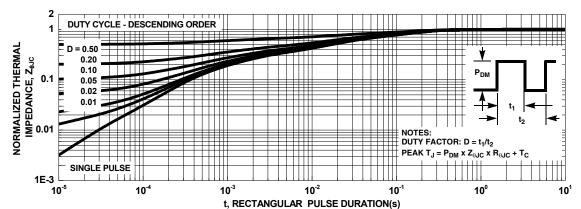


Figure 3. Normalized Maximum Transient Thermal Impedance

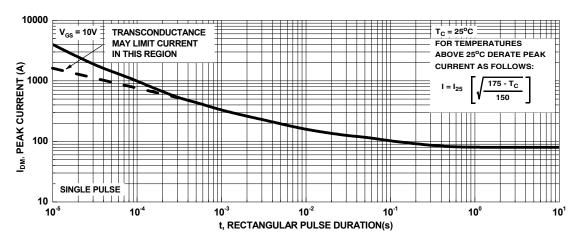


Figure 4. Peak Current Capability

Typical Characteristics

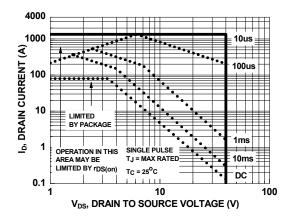
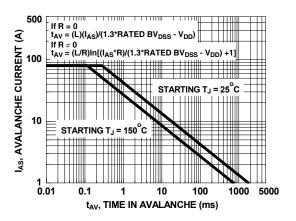
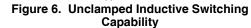


Figure 5. Forward Bias Safe Operating Area



NOTE: Refer to Fairchild Application Notes AN7514 and AN7515



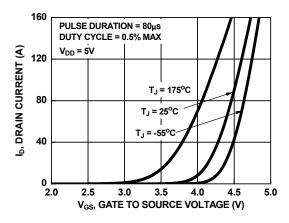


Figure 7. Transfer Characteristics

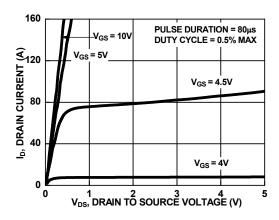


Figure 8. Saturation Characteristics

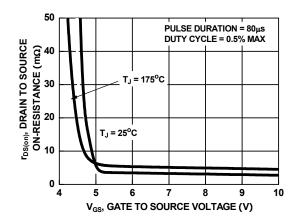


Figure 9. Drain to Source On-Resistance Variation vs Gate to Source Voltage

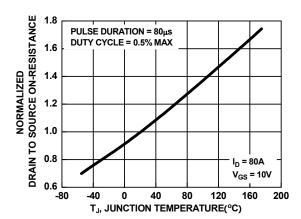


Figure 10. Normalized Drain to Source On Resistance vs Junction Temperature

Typical Characteristics

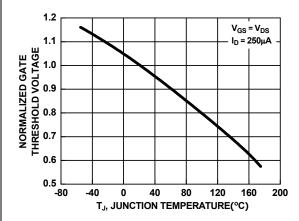


Figure 11. Normalized Gate Threshold Voltage vs
Junction Temperature

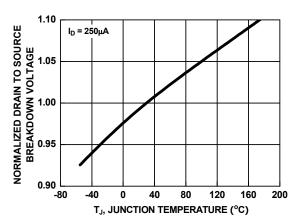


Figure 12. Normalized Drain to Source Breakdown Voltage vs Junction Temperature

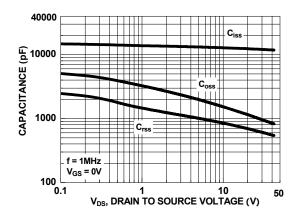


Figure 13. Capacitance vs Drain to Source Voltage

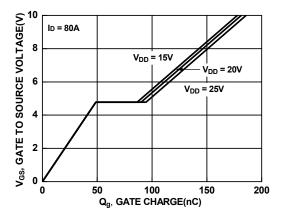


Figure 14. Gate Charge vs Gate to Source Voltage





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